

ABSTRACT OF THE DISCLOSURE

An abrasive molding consisting essentially of inorganic particles having an average particle diameter in the range of $0.005\ \mu\text{m}$ to $0.3\ \mu\text{m}$, and having a relative density in the range of 45% to 90%, provided that pores having a diameter of at least $0.5\ \mu\text{m}$ are excluded from the molding. The abrasive molding is used for polishing a material to be polished by using a polishing liquid, preferably water or an aqueous solution of an alkali metal hydroxide, which does not contain a loose abrasive grain.

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